L Numbe	r Hits	Search Text	l DB	Time stamp
1	16	UHV same susceptor	USPAT;	2003/04/04 10:02
]			US-PGPUB;	1
			EPO; JPO;	
1			DERWENT; IBM TDB	
3	1	batch same susceptor and UHV	USPAT;	2003/04/04 10:05
İ		• • • • • • • • • • • • • • • • • • • •	US-PGPUB;	2003/04/04 10:03
			EPO; JPO;	
			DERWENT;	
4	93	batch same susceptor and CVD	IBM_TDB	
1		bacch same susceptor and CVD	USPĀT;	2003/04/04 10:06
}			US-PGPUB; EPO; JPO;	
			DERWENT;	
ا د		1,	IBM TDB	
5	9	batch same susceptor same horizontal\$4 and CVD	USPAT;	2003/04/04 10:19
		CVD	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
6	24	(planarty or planetary) same susceptor	USPAT;	2003/04/04 11:41
			US-PGPUB;	
	-		EPO; JPO;	
			DERWENT;	
12	32	susceptor same (temperature or thermal)	IBM_TDB USPAT;	2002/04/04 12 54
		near5 (control\$4 or monitor\$4) same	US-PGPUB;	2003/04/04 13:54
1		(sensor or thermocouple) and cvd.ti.	EPO; JPO;	
1	ĺ		DERWENT;	
13	28		IBM_TDB	
13	28	susceptor same (temperature or thermal) near5 (control\$4 or monitor\$4) same	USPAT;	2003/04/04 13:56
		(sensor or thermocouple) same vacuum and	US-PGPUB; EPO; JPO;	
		cvd	DERWENT;	
			IBM TDB	
14	5		USPAT;	2003/04/04 13:58
		near5 (control\$4 or monitor\$4) same	US-PGPUB;	
		(sensor or thermocouple) same vacuum and	EPO; JPO; DERWENT;	
		ova ana bacch	IBM TDB	
18	1	procedure of the procedure of the procedure	USPAT;	2003/04/04 14:00
	1	same (sensor or thermocouple) and cvd	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
37	4	deep adj trench same CVD and @py<2001 and	USPAT;	2003/04/04 15:11
		UHV STEEL ST	US-PGPUB;	2003/04/04 13:11
			EPO; JPO;	
			DERWENT;	
38	2	deep adj trench same CVD same vacuum and	IBM_TDB	2002/04/04 15:11
		epy<2001	USPAT; US-PGPUB;	2003/04/04 15:11
			EPO; JPO;	
]		DERWENT;	
39		dans and known to the	IBM_TDB	
39	1	deep adj trench same CVD and @py<2001 and 117/\$4.ccls.	USPAT;	2003/04/04 15:13
		11// 43.0013.	US-PGPUB; EPO; JPO;	
			DERWENT;	
4.0			IBM_TDB	
40	83	deep adj trench same CVD and @py<2001 and	USPAT;	2003/04/04 15:26
		438/\$4.ccls.	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
41	110	(ald or atomic adj layer adj deposit\$4)	USPĀT;	2003/04/04 15:28
		same Si	US-PGPUB;	
]		EPO; JPO;	
			DERWENT; IBM TDB	
	·			

42	2	(ald or atomic adj layer adj deposit\$4) same Si and UHV	USPAT; US-PGPUB;	2003/04/04 15:29
			EPO; JPO; DERWENT; IBM TDB	
43	29	(ald or atomic adj layer adj deposit\$4 or ale) and UHV	USPAT; US-PGPUB;	2003/04/04 15:32
			EPO; JPO; DERWENT;	
73	10	ale and suntola.in.	IBM_TDB USPAT;	2003/04/04 15:42
			US-PGPUB; EPO; JPO; DERWENT;	
74	3	(ald or atomic adj layer adj deposit\$4 or	IBM_TDB USPAT;	2003/04/04 15:33
		ale) same UHV	US-PGPUB; EPO; JPO;	2000, 01, 01 13.33
75			DERWENT; IBM_TDB	
/5	3	(ald or atomic adj layer adj epitax\$4 or ale) same UHV	USPAT; US-PGPUB;	2003/04/04 15:37
			EPO; JPO; DERWENT;	
76	458	(ald or atomic adj layer adj epitax\$4 or ale) same vacuum	IBM_TDB USPAT; US-PGPUB;	2003/04/04 15:37
			EPO; JPO; DERWENT;	
_	9	hans.in. and buschbeck.in.	IBM_TDB USPAT;	2003/04/02 15:28
			US-PGPUB; EPO; JPO;	
_		//IIIV on other odi bish odi	DERWENT; IBM_TDB	
		((UHV or ultra adj high adj vacuum) same (CVD or chemical adj vapor adj deposit\$4) or UHV\$1CVD) same batch and (treat\$4 or	USPAT; US-PGPUB; EPO; JPO;	2003/03/25 13:08
		clean\$4) same vacuum	DERWENT; IBM TDB	
-	7	(CVD or chemical adj vapor adj deposit\$4)	USPAT; US-PGPUB;	2003/03/25 13:09
		or UHV\$1CVD) same batch	EPO; JPO; DERWENT;	
-	10	(hydrogen or "h.sub.2") near4 plasma same clean\$4 same (ev)	IBM_TDB USPAT;	2003/04/03 11:04
		Cleany4 Same (ev)	US-PGPUB; EPO; JPO; DERWENT;	
_	4	(hydrogen or "h.sub.2") near4 plasma same	IBM_TDB USPAT;	2003/04/03 11:07
		(ev) same (wafer or substrate) same oxide	US-PGPUB; EPO; JPO;	
_	48	(hudrager or "h cub 2") reem aleem	DERWENT; IBM_TDB	2002/04/02 11 07
	40	<pre>(hydrogen or "h.sub.2") near4 plasma same (ev) same (wafer or substrate)</pre>	USPAT; US-PGPUB; EPO; JPO;	2003/04/03 11:07
			DERWENT; IBM TDB	
_	21	<pre>(hydrogen or "h.sub.2") near4 plasma near20 (ev) same (clean\$4 or passivat\$4 or</pre>	USPAT; US-PGPUB;	2003/04/03 11:32
		oxide)	EPO; JPO; DERWENT;	
-	24	(hydrogen or "h.sub.2") near4 plasma near10 energy same (clean\$4 or passivat\$4	IBM_TDB USPAT;	2003/04/03 11:42
		or native adj oxide) same (wafer or substrate)	US-PGPUB; EPO; JPO; DERWENT;	
			IBM_TDB	

-	8	i tomb of all of acomic day layer day	USPAT;	2003/04/03 13:25
		(epitax\$4 or deposit\$4)) same (UHV or	US-PGPUB;	
		ultra adj high adj vacuum)	EPO; JPO;	
İ			DERWENT;	
			IBM TDB	
-	78	(CVD or chemical adj vapor adj deposit\$4)	USPAT;	2003/04/03 14:28
	[and vertical same horizontal same batch	US-PGPUB;	
	l		EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	11	i terri da datea dej magni dei vecedin negli	USPAT;	2003/04/03 15:06
		(CVD or chemical adj vapor adj deposit\$4))	US-PGPUB;	1 = 1 = 1, 1 = 1, 1 = 13.00
		same vertical same horizontal	EPO; JPO;	i
			DERWENT;	
			IBM TDB	
-	1	(UHV or ultra adj high adj vacuum near4	USPAT;	2003/04/03 14:40
]		(CVD or chemical adj vapor adj deposit\$4))	US-PGPUB;	
1		same vertical near5 reactor	EPO; JPO;	
			DERWENT;	
]			IBM TDB	
-	56	i toni or artra aaj migh aaj vacaam neard	USPAT;	2003/04/03 15:13
	1	(CVD or chemical adj vapor adj deposit\$4))	US-PGPUB;	
		and (vacuum near10 (furnace or heater))	EPO; JPO;	
	1		DERWENT;	
			IBM TDB	
_	2	5755938.pn.	USPĀT;	2003/04/03 16:09
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	85	temperature near10 control near10	USPĀT;	2003/04/04 10:00
		distribution same (reactor or chamber) and	US-PGPUB;	
		(CVD or chemical adj vapor adj deposition)	EPO; JPO;	
			DERWENT;	
			IBM TDB	